Module 2

# Lesson 2 part 2

Note: If this process is not done properly then the wafer will break as it is subjected to a lot of stress.

1. Now we tape frame the backside of the wafer. This mechanically supports the wafer.
2. Now we will dice the wafer as we know there are many dies on the wafer. This is a 2-step process unless you go with the blade directly. But direct blade slicing has a lot of cons. Therefore we first use laser grooving to create marks/ grooves for the blade to follow.

Link for video:

<https://drive.google.com/file/d/1RNSt-A62O7AdWDILbVOuuXaSkpyjOa-1/view?usp=sharing>